# LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司



WEB: <a href="https://www.winstar.com.tw">https://www.winstar.com.tw</a> E-mail: sales@winstar.com.tw

### **SPECIFICATION**

MODULE NO.:	WO2004B	-NFH#
APPROVED BY:  ( FOR CUSTOMER USE ONLY )	PCB VERSION:	DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2022/09/23		First issue

Winstar Display Co.,				MODLE NO:
華,	凌光電股份有限	公司		
REC	ORDS OF REV	ISION		DOC. FIRST ISSUE
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### 1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type, X→TAB Type, O→COG Type

③ Display Font: 20 \* 04 dot

Model serials no.

 $\bigcirc$  Backlight Type: N $\rightarrow$ Without backlight T $\rightarrow$ LED, White L $\rightarrow$ LED, Full color

 $B\rightarrow EL$ , Blue green  $A\rightarrow LED$ , Amber  $J\rightarrow DIP$  LED, Blue  $D\rightarrow EL$ , Green  $R\rightarrow LED$ , Red  $K\rightarrow DIP$  LED, White

W→EL, White O→LED, Orange E→DIP LED, Yellow Green

 $M\rightarrow$ EL, Yellow Green  $G\rightarrow$ LED, Green  $H\rightarrow$ DIP LED, Amber  $F\rightarrow$ CCFL, White  $P\rightarrow$ LED, Blue  $I\rightarrow$ DIP LED, Red

 $Y \rightarrow LED$ , Yellow Green  $X \rightarrow LED$ , Dual color  $G \rightarrow LED$ , Green  $C \rightarrow LED$ , Full color

© LCD Mode : B→TN Positive, Gray V→FSTN Negative, Blue

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$  Positive, Gray  $F \rightarrow FSTN$  Positive  $I \rightarrow HTN$  Negative, Black  $K \rightarrow FSC$  Negative  $U \rightarrow HTN$  Negative, Blue  $S \rightarrow FSC$  Positive

M→STN Negative, Blue E→ISTN Negative, Black
G→STN Positive, Gray C→CSTN Negative, Black
Y→STN Positive, Yellow Green A→ASTN Negative, Black

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

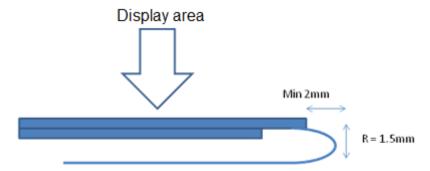
Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00 direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00 L→Transmissive, W.T, 6:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00 E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code #:Fit in with the ROHS Directions and regulations

### 2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) The limitation of FPC bending



(12)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

# **3.General Specification**

Item	Dimension	Unit				
Module dimension	66.1 x 34.2 x 2.9(MAX)	mm				
View area	60.5 x 22.18	mm				
Active area	58.5 x 20.18	mm				
Dot size	0.45x 0.54	mm				
Dot pitch	0.50 x 0.59	mm				
Character size	2.45 x 4.67	mm				
Character pitch	2.95 x 5.17	mm				
LCD type	FSTN Positive Transflective  (In LCD production, It will occur slightly color difference. We can only guarantee the same color in the same batch.)					
Duty	1/33DUTY,1/6BIAS					
View direction	6 o'clock					
Backlight Type	Without backlight					
IC	IST3602					
Interface	I2C					

# **4.Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	ТОР	-20	_	+70	$^{\circ}\!$
Storage Temperature	TST	-30	_	+80	$^{\circ}$
Input Voltage	VIN	-0.3	_	V <sub>DD</sub> +0.3	V
Power Supply Voltage	$V_{ m DD}$	-0.3	_	4.0	V
LCD Driver Voltage	VLCD	-0.3	_	18.0	V

# **5.Electrical Characteristics**

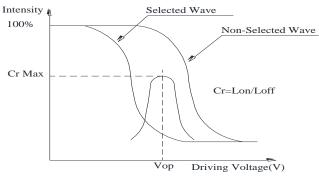
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$ m V_{DD}$	_	2.7	3.0	3.3	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCD	$V_{O}$ - $V_{SS}$	Ta=25°C	7.6	7.8	8.0	V
		Ta=70°C	_	_	_	V
Input High Volt.	$V_{ m IH}$	_	0.8 V <sub>DDIO</sub>	_	$V_{ m DD}$	V
Input Low Volt.	$V_{IL}$	_	$V_{SS}$	_	$0.2~\mathrm{V_{DD}}$	V
Output High Volt.	$V_{\mathrm{OH}}$	_	0.8 V <sub>DDIO</sub>	_	$V_{DD}$	V
Output Low Volt.	$V_{\mathrm{OL}}$	_	_	_	$0.2~\mathrm{V_{DD}}$	V
Supply LCM current	IDD	VDD=3.0V	_	0.5	_	mA

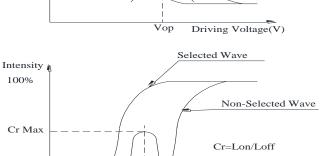
Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

## **6.Optical Characteristics**

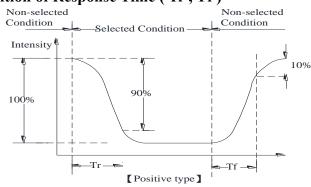
Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	30	$\phi = 180^{\circ}$
	θ	CR≧2	0	_	60	$\phi = 0^{\circ}$
View Angle	θ	CR≧2	0	_	45	$\phi = 90^{\circ}$
	θ	CR≧2	0	_	45	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	_	5	_	_
р т.	T rise	_	_	150	200	ms
Response Time	T fall	_	_	150	200	ms

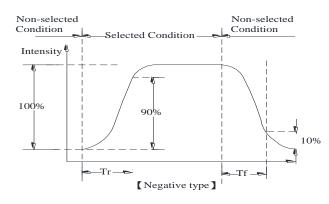
### **Definition of Operation Voltage (Vop)**





#### **Definition of Response Time (Tr, Tf)**





#### **Conditions:**

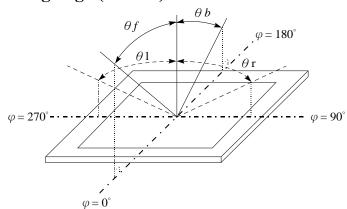
Operating Voltage: Vop

Driving Voltage(V)

Vop Viewing Angle( $\theta$ ,  $\varphi$ ):  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

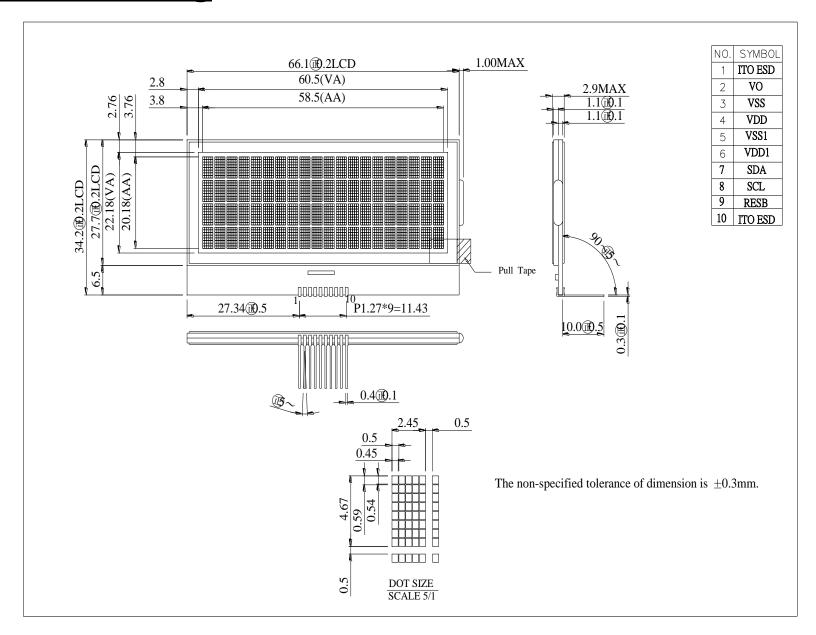
### Definition of viewing angle( $CR \ge 2$ )



# **7.Interface Pin Function**

Pin	Symbol	<b>Function Description</b>
1	ITO ESD	Ground
2	V0	LCD Power Supply
3	VSS	Ground(VSS2&VSS3)
4	VDD	Power Supply(VDD2&VDD3)
5	VSS1	Ground(VSS1)
6	VDD1	Power Supply(VDD1)
7	SDA	Serial input data
8	SCL	Serial input clock
9	RESB	Hardware Reset input pin
10	ITO ESD	Ground

## **8.Contour Drawing**



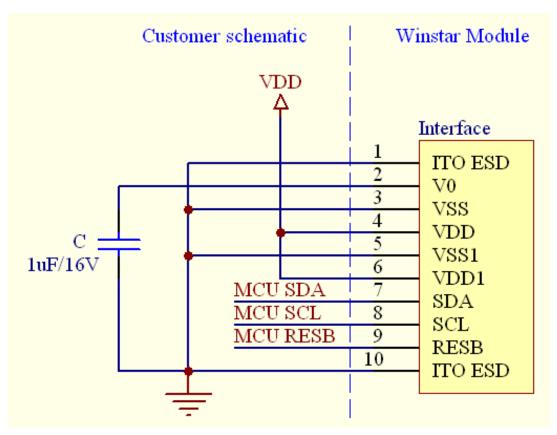
```
8.1. Initial code
void Initial(void)
   RST = 1:
   delay ms(10);
   RST = 0;
   delay_ms(10);
   RST = 1:
   delay ms(10);
   Start();
                 //i2c start
   Write byte(0x78); // salve address
      __.
   // IS Instruction Table 0
   WriteIns(0x20); //Function Set
   WriteIns(0x01);
                //Clear Display
   delay ms(20);
   WriteIns(0x90);
                 //Set DDRAM address
   WriteIns(0x00);
                 //Set DDRAM address
   WriteIns(0x06);
                 //Set Entry Mode
   WriteIns(0x0C);
                 //Display Control
// IS Instruction Table 1
   WriteIns(0x21);
                 //Function Set : 0 0 1 0 0 0 IS2 IS1
   WriteIns(0x12);
                 //Follows Control :0 0 0 1 0 0 BS2 BS1
                                                   Bias select: 1/6B
   WriteIns(0x40):
                 //Set ICON RAM Address
   WriteIns(0x30);
                 //Power Control 1
                                 :0011000SLEEP
   WriteIns(0x6F);
                 //ICON/Power Control2
   WriteIns(0x70);
                 //Set booster ;V0 Control 2
   delay ms(100);
// IS Instruction Table 3
   WriteIns(0x23); //Function Set : 0 0 1 0 0 0 IS2 IS1
   WriteIns(0x81);
                 //Contrast: VOP SET
   WriteIns(0x27);
                  // VOP SET
   WriteIns(0x82);
                  //start line setting
   WriteIns(0x00);
                  //start line setting : 0 0 ST[5:0]
   WriteIns(0xA7);
                  //Rgain set :1 0 1 0 RR[3:0]
// IS Instruction Table 2
   WriteIns(0x22); //Function Set : 0 0 1 0 0 0 IS2 IS1
   WriteIns(0x60):
                 //Set Display pattern : 0 1 1 0 0 0 INV AP
                 //Set Display Mode
   WriteIns(0x13):
                                  :0 0 0 1 DH1 DH0 N2 N1
                                                         1/33D
                 //Select CGRAM & COM/SEG direction
   WriteIns(0x44);
// IS Instruction Table 3
   WriteIns(0x23);
                    //Function Set : 0 0 1 0 0 0 IS2 IS1
   WriteIns(0x88);
                    // Set 88H 4 times to entry IST test command mode
   WriteIns(0x88);
```

```
WriteIns(0x88);
   WriteIns(0x88);
   WriteIns(0x28);
                     //Frame rate adjusting enable
   WriteIns(0xB2);
                     //1st Frame rate control
   WriteIns(0xEF);
                     //2nd LN[7:0]
   WriteIns(0x00);
                     //3rd LN[15:8]
                                   95Hz
                     //OSC Clock Select
   WriteIns(0x93);
                                      :Fosc/1
   WriteIns(0x99);
                     //OSC Divide Select :750KHz
   WriteIns(0xE3);
                     //Exit IST test command
Stop();
                     //i2c_stop
}
```

#### \*NOTE:

This Initial code is a suggested value, and customers can change the parameters according to a ctual needs.

### 8.2. APPLICATION EXAMPLES



## 9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test							
Test Item	Content of Test	Test Condition	Not e					
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2					
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2					
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	_					
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1					
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2					
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles						
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	2					
Static electricity test	Endurance test applying the electric stress to the terminal.	VS= $\pm600$ V(contact), $\pm800$ v(air), RS= $330\Omega$ CS= $150$ pF 10 times						

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

# **10.Inspection specification**

No	Item			Criterion		AQL
01	Electrical Testing	Missing vertical, horizontal segment, segment contrast defect.  Missing character, dot or icon.  Display malfunction.  No function or no display.  Current consumption exceeds product specifications.  LCD viewing angle defect.  Mixed product types.  Contrast defect.				0.65
02	Black or white spots on LCD (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> <li>3.1 Round type: As following drawing</li> </ul>				2.5
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type: $\Phi = (x + y)/2$ $X$ 3.2 Line type: (A)	¥ ¥	Size $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$ ring drawing)	Acceptable QTY Accept no dense 2 1 0 Acceptable QTY Acceptable QTY Accept no dense	2.5
		→1 L 1←	L≦3.0 L≦2.5		As round type	2.5
04	Polarizer bubbles	If bubbles are virgudge using black specifications, not to find, must che specify direction	k spot ot easy eck in	Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5

No	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD blac	k spots, white spots, cor	ntamination	
06	Chipped glass	k: Seal width t: L: Electrode pad length  6.1 General glass chip: 6.1.1 Chip on panel surf  z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$	Glass thickness a: LC:	$x: Chip length$ $x \le 1/8a$ $x \le 1/8a$	2.5
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x ≤ 1/8a	
		$1/2t < z \leq 2t$	Not exceed 1/3k	x≤1/8a	
		⊙ If there are 2 or more	chips, x is the total leng	gth of each chip.	

No	Item	Criterion					
No 06	Glass	remain and be inspected.  OIf the product will be damaged.	y: Chip width t: Glass thickness gth terminal: ode pad: $x$ : Chip length $x \le 1/8a$ The portion: $x \le 1/8a$ The portion: $x \le 1/8a$ The portion of the properties of th	z: Chip thick a: LCD side  z: th z: th z: th z: th z: trode termine customer, the	Chip thickness $0 < z \le t$ Chip thickness $0 < z \le t$ Chip thickness $0 < z \le t$ /3 of the ITO must al specifications.		

No	Item	Criterion	
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
		8.1 Illumination source flickers when lit.	
0.0	Backlight	8.2 Spots or scratched that appear when lit must be judged. Using	
08	elements	LCD spot, lines and contamination standards.	
		8.3 Backlight doesn't light or color wrong.	
		9.1 Bezel may not have rust, be deformed or have fingerprints,	
09	Bezel	stains or other contamination.	
		9.2 Bezel must comply with job specifications.	0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or	2.5
		contamination.	
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height	0.65
		indicated in the assembly diagram.	
		10.4 There may not be more than 2mm of sealant outside the seal	2.5
		area on the PCB. And there should be no more than three places.	
		10.5 No oxidation or contamination PCB terminals.	
		10.6 Parts on PCB must be the same as on the production	2.5
10	PCB · COB	characteristic chart. There should be no wrong parts, missing parts or excess parts.	0.65
		10.7 The jumper on the PCB should conform to the product	
		characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	
		screw hold pad, make sure it is smoothed down.	2.5
		10.9 The Scraping testing standard for Copper Coating of PCB	
		X	2.5
		$X * Y \leq 2mm^2$	
		11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections, oxidation	
11	Soldering	or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin	2.5
		(OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin	2.5
		must be present or look as if it cause the interface pin to sever.	
	General appearance	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12		component) is not burned into brown or black color.	
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

## 11.Material List of Components for

## **RoHs**

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited	100	1000	1000	1000	1000	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm
Above limited value is set up according to RoHS.										

2. Process for RoHS requirement : (only for RoHS inspection)

(1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.

(2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

# 12.Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

ule Number:			Page: 1
• <u>Panel Specification</u> :  1. Panel Type:	Pass		
<b>J</b> 1		□ NG ,	
	☐ Pass ☐ Pass	□ NG ,	
		□ NG ,	
4. View Area:	☐ Pass	□ NG ,	
5. Active Area:	☐ Pass	□ NG ,	
6. Operating Temperature:	☐ Pass	□ NG ,	
7. Storage Temperature:	Pass	□ NG ,	
8. Others:			
Mechanical Specification: PCB Size:	Dogg		
	☐ Pass	□ NG ,	
2. Frame Size: 3. Materal of Frame:	☐ Pass ☐ Pass	□ NG ,	
	☐ Pass	□ NG ,	
	☐ Pass	□ NG ,	
<ul><li>5. Fix Hole Position :</li><li>6. Backlight Position :</li></ul>	☐ Pass	□ NG ,	
7. Thickness of PCB:	☐ Pass	□ NG ,	
8. Height of Frame to PCB:	☐ Pass		
9. Height of Module:	☐ Pass	□ NG ,	
10. Others:	Pass	□ NG ,	
Relative Hole Size:	1 000		
Pitch of Connector:	Pass	□ NG ,	
. Hole size of Connector:	☐ Pass	□ NG ,	
Mounting Hole size:	Pass	□ NG ,	
. Mounting Hole Type:	Pass	☐ NG ,	
. Others:	Pass	☐ NG ,	
Backlight Specification:	1 400		
B/L Type:	Pass	□ NG ,	
B/L Color:	Pass	☐ NG ,	
. B/L Driving Voltage (Refere			
B/L Driving Current:	Pass	☐ NG ,	
5. Brightness of B/L:	☐ Pass	☐ NG ,	
6. B/L Solder Method:	Pass	☐ NG ,	
7. Others:	Pass	☐ NG ,	



	winstar		
Modu	le Number:		Page: 2
5、	Electronic Characteristics of	Module:	
1.	Input Voltage:	Pass	□ NG ,
2.	Supply Current:	Pass	☐ NG ,
3.	Driving Voltage for LCD:	Pass	☐ NG ,
4.	Contrast for LCD:	Pass	☐ NG ,
5.	B/L Driving Method:	Pass	□ NG ,
6.	Negative Voltage Output:	Pass	☐ NG ,
7.	Interface Function:	Pass	☐ NG ,
8.	LCD Uniformity:	Pass	□ NG ,
9.	ESD test:	Pass	☐ NG ,
10.	Others:	Pass	☐ NG ,
6、	Summary:		
	Sales signature:		<b>Date:</b> / /